

US00D822629S

(12) **United States Design Patent** (10) **Patent No.:** **US D822,629 S**
Kimura et al. (45) **Date of Patent:** **** Jul. 10, 2018**

(54) **SEMICONDUCTOR PACKAGE**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**

USPC D13/182; 257/678, 684, 690, 691;
361/679.01, 713, 728, 736, 760, 761, 772,
361/775, 783, 820; 174/250, 253;
438/15, 25, 26, 51, 55, 63, 64, 106
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;
H01L 2021/00; H01L 2021/02; H01L
2021/04; H01L 21/4814; H01L 21/4846;
H01L 21/4871; H01L 21/67144; H01L
23/02; H01L 23/13; H01L 23/14; H01L
23/147; H01L 2924/171; H01L
2924/1711; H01L 2924/1715; H01L
2924/17151; H01L 2924/181; H01L
2924/1811; H01L 2924/1815; H01L
2924/19042; H01L 2924/1905; H01L
2224/08054; H01L 23/58; H05B 41/14;
H02B 6/4201; G02B 6/4256; G02B
6/4257; G02B 6/4261; G02B 6/4262;
G02B 6/428;

(Continued)

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(74) *Attorney, Agent, or Firm* — Kenja IP Law PC

(57) **CLAIM**

The ornamental design for a semiconductor package, as
shown and described.

DESCRIPTION

FIG. 1 is a top perspective view of a semiconductor package
showing our new design;

FIG. 2 is a bottom perspective view thereof;

FIG. 3 is a front view thereof;

FIG. 4 is a rear view thereof;

FIG. 5 is a right side view thereof;

FIG. 6 is a top view thereof;

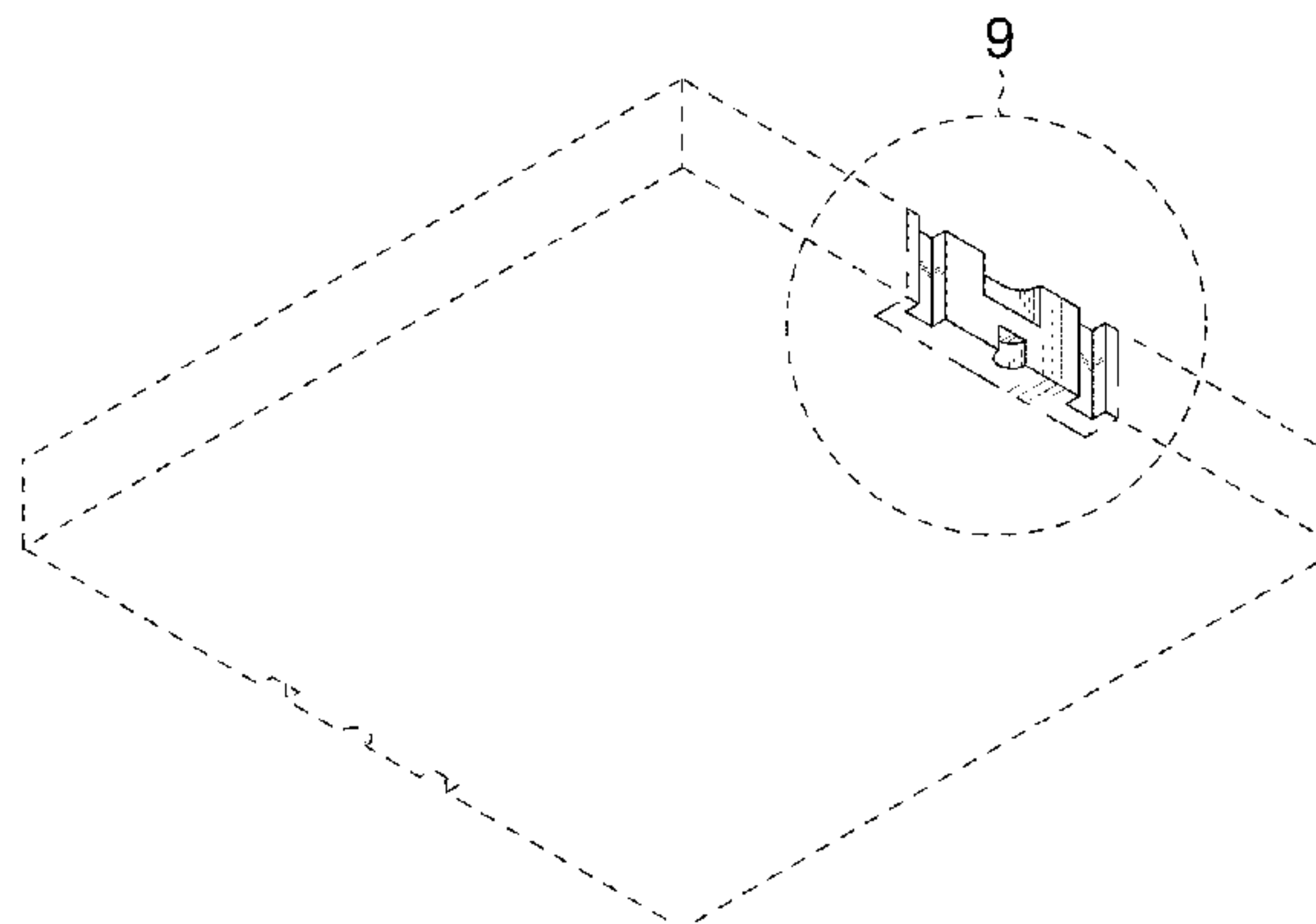
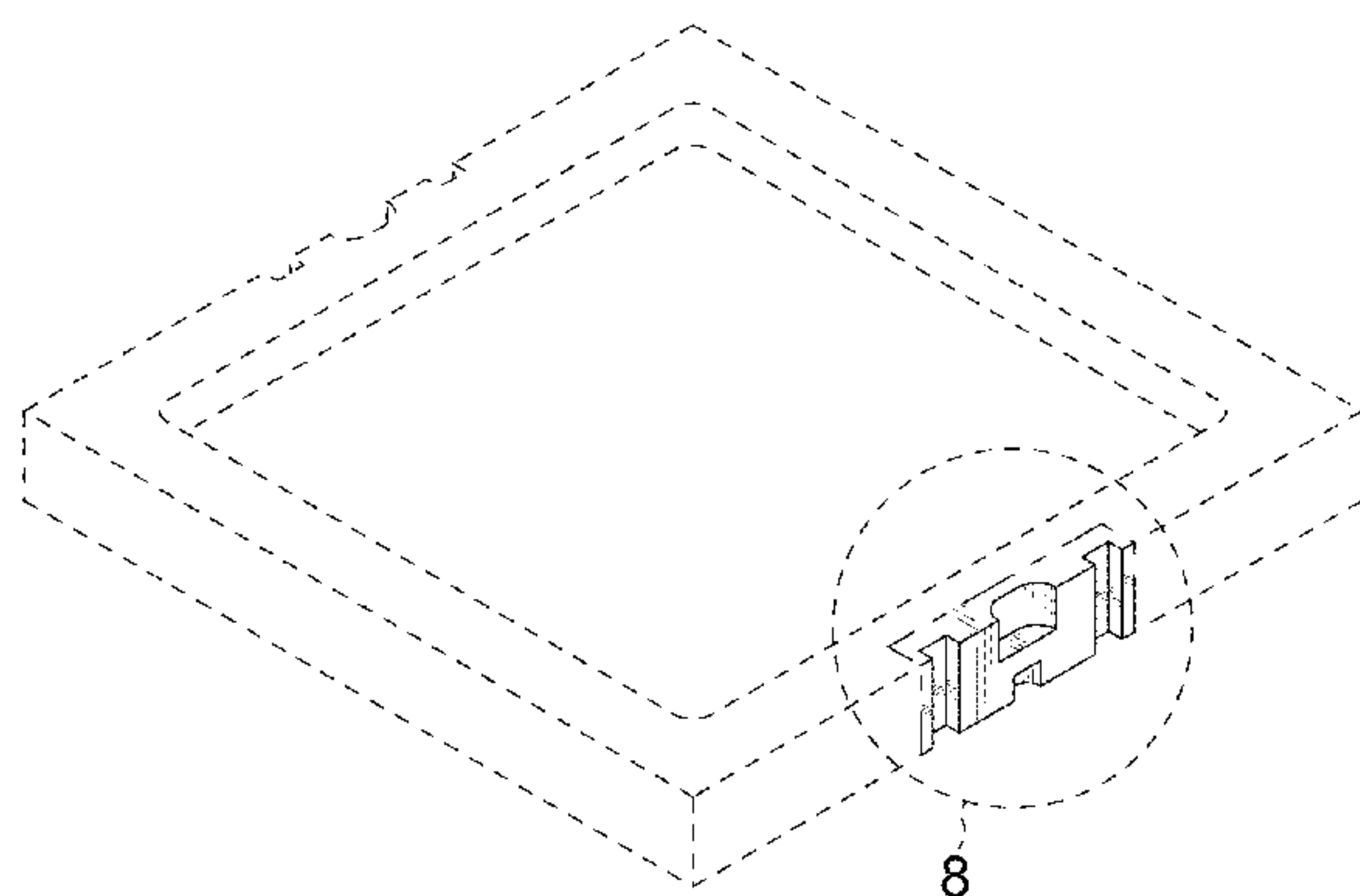
FIG. 7 is a bottom view thereof;

FIG. 8 is an enlarged portion view labeled 8 taken in FIG.
1;

FIG. 9 is an enlarged portion view labeled 9 taken in FIG.
2; and,

FIG. 10 is another perspective view thereof shown in a used
condition in which the semiconductor package is sealed and
mounted onto a substrate which is shown in broken lines.
The broken lines in the drawings illustrate portions of the
semiconductor package which form no part of the claimed
design. The dot-dashed lines in the drawings are for the
purpose of showing boundaries of the design and form no
part of the claimed design.

1 Claim, 10 Drawing Sheets



(58) Field of Classification Search

CPC G02B 6/4281; H05K 1/14; H05K 1/141;
H05K 1/142; H05K 1/144; H05K 1/18;
H05K 1/181; H05K 1/182; H05K 1/026
See application file for complete search history.

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FIG. 1

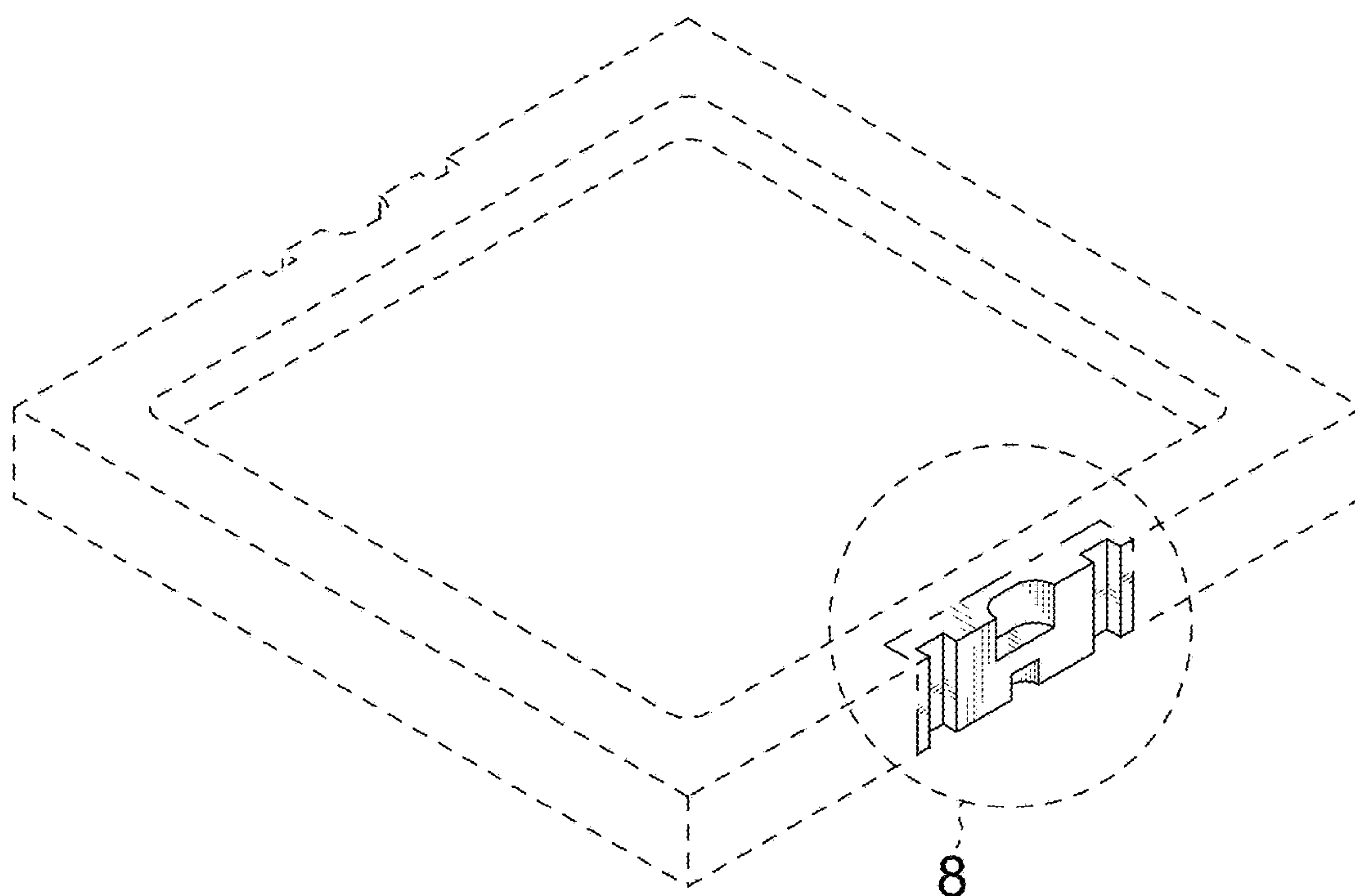


FIG. 2

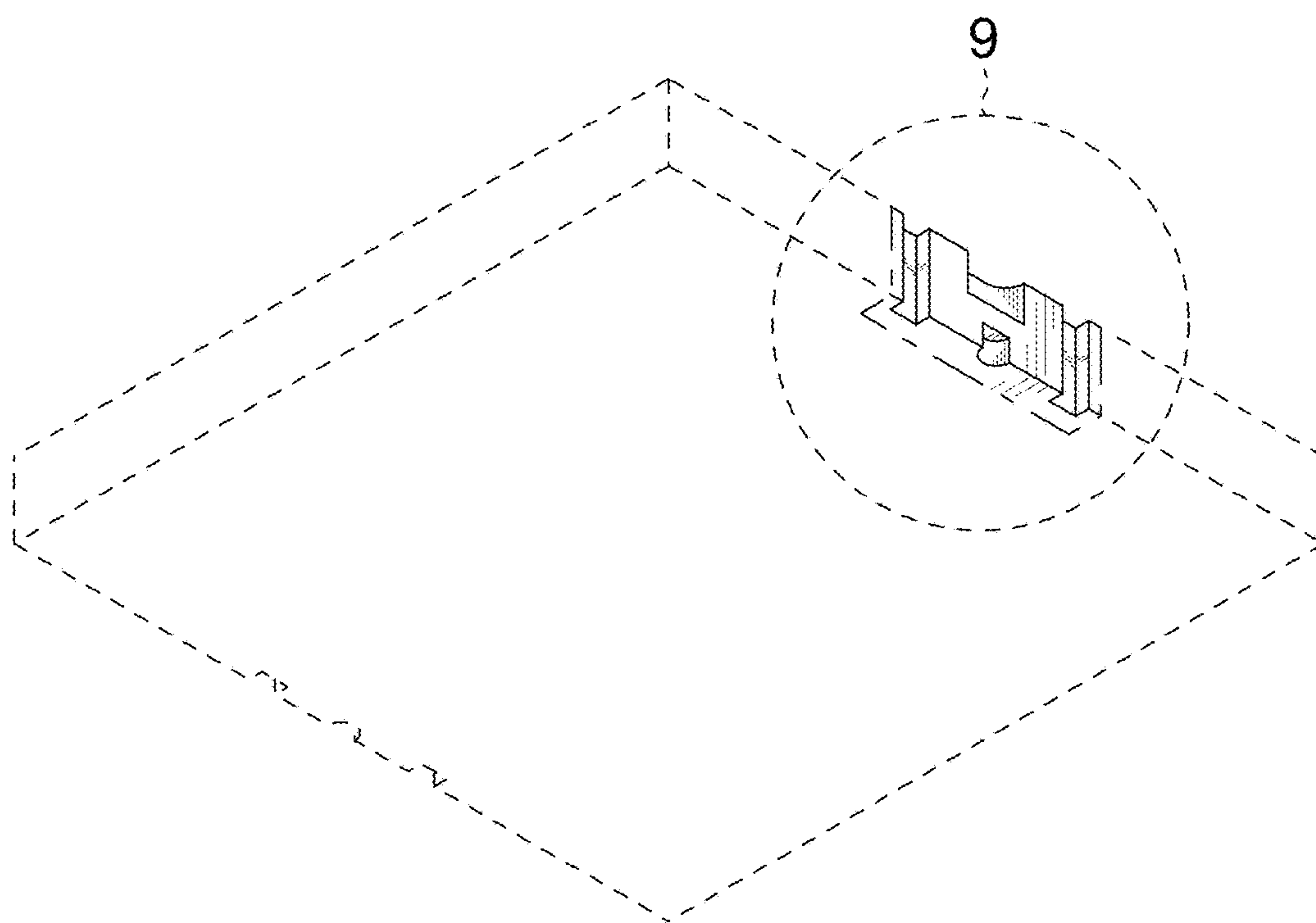


FIG. 3

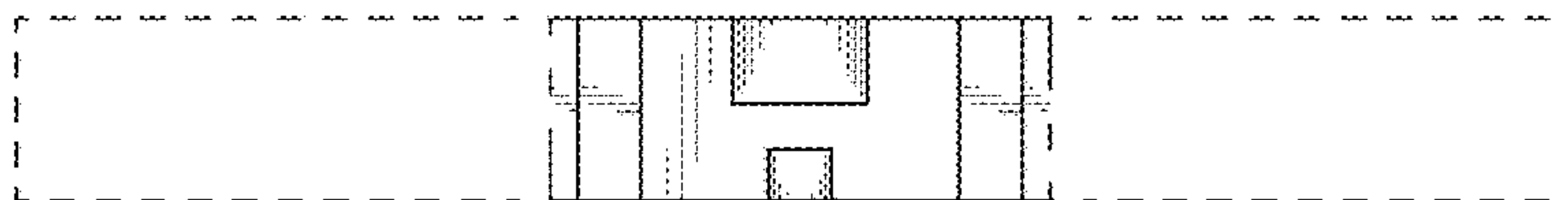


FIG. 4



FIG. 5



FIG. 6

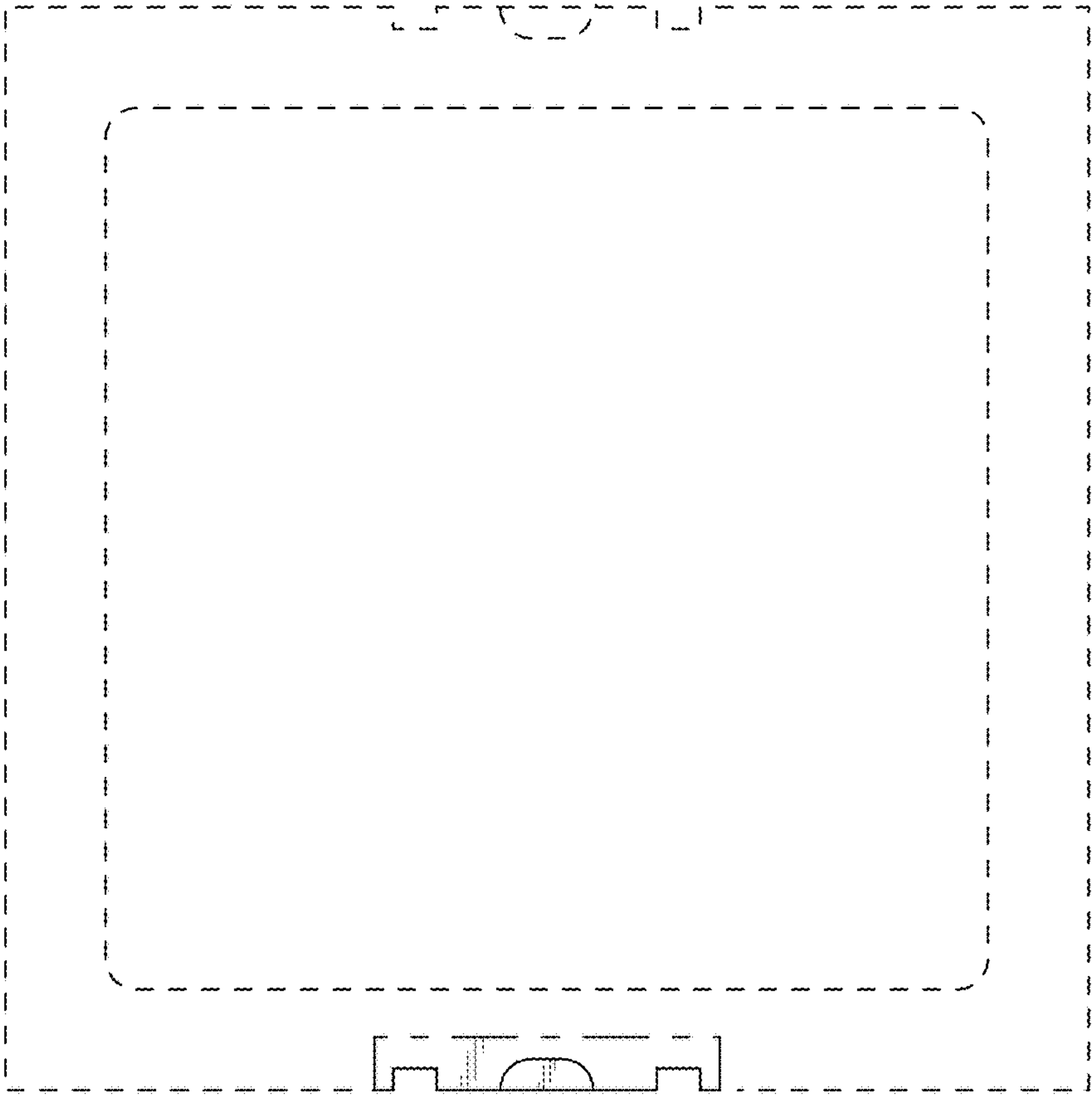


FIG. 7

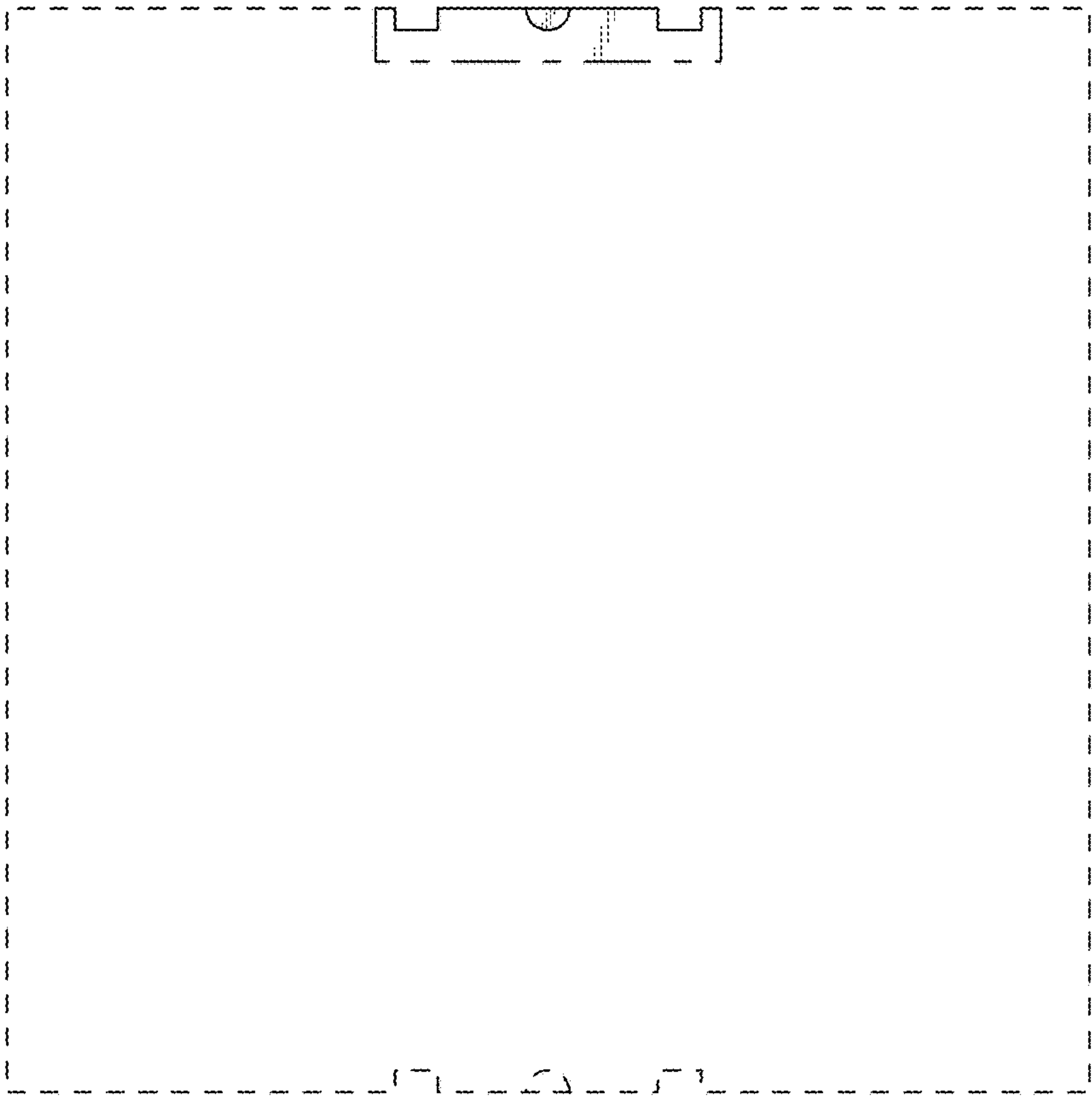


FIG. 8

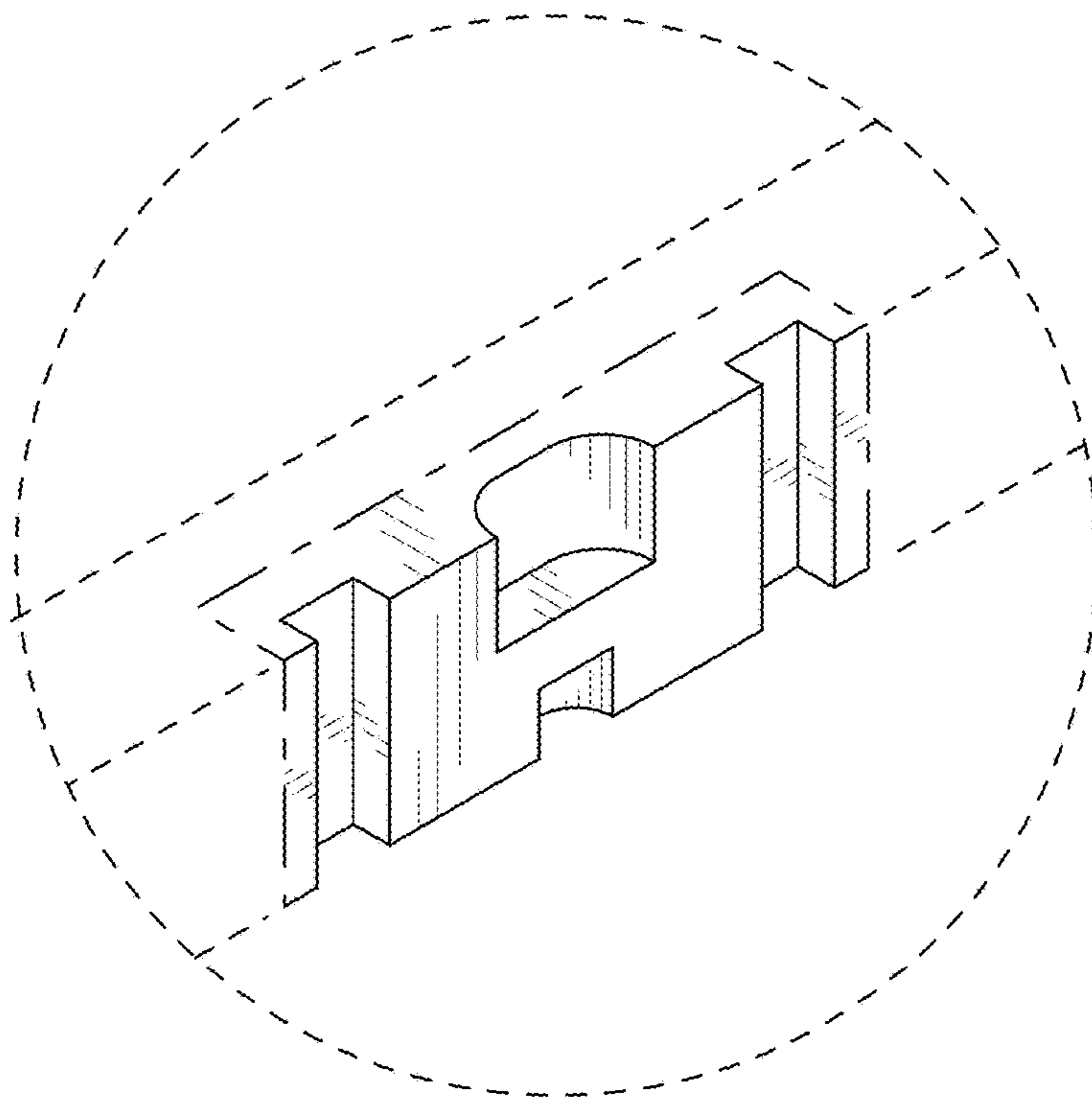


FIG. 9

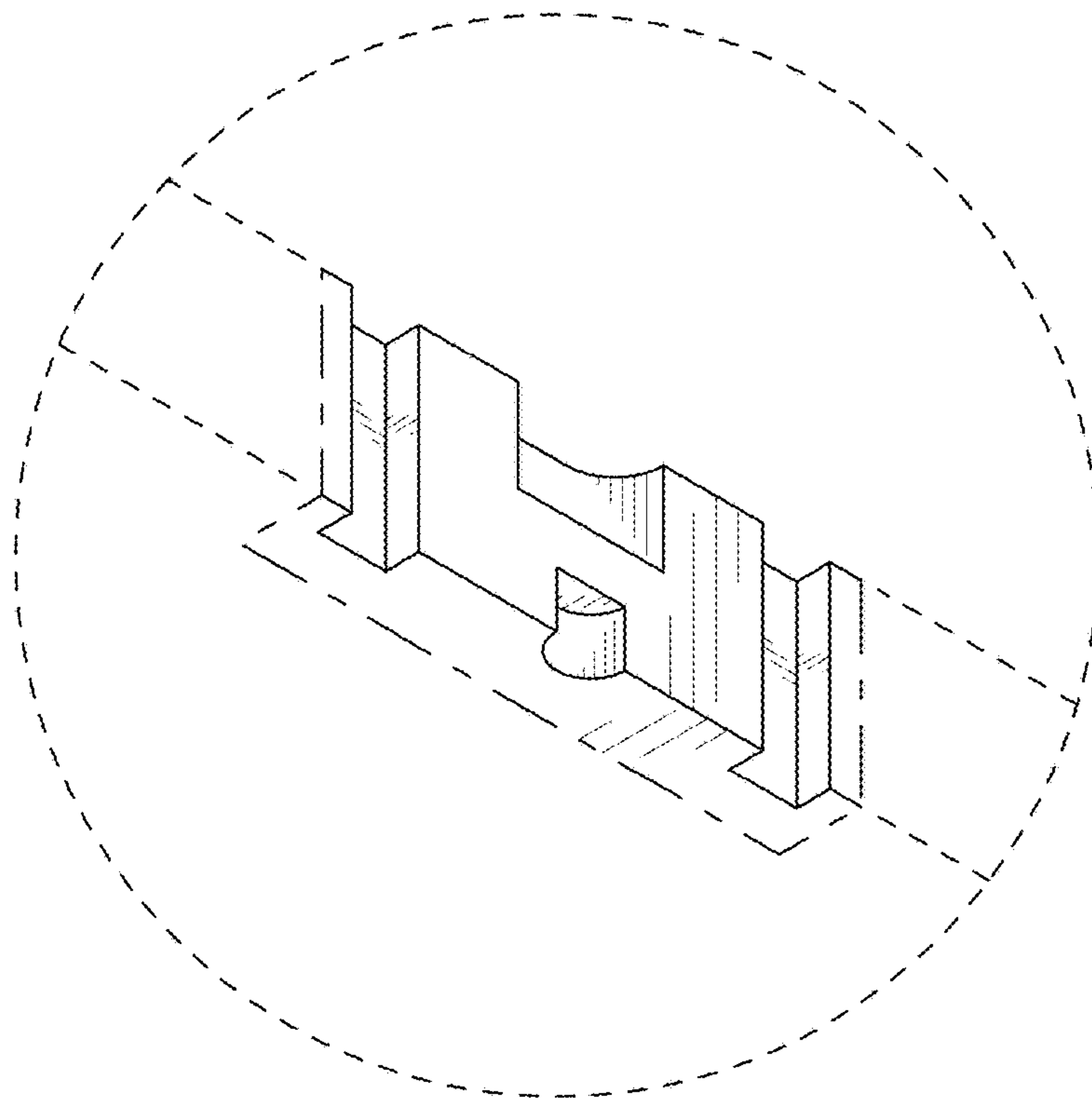


FIG. 10

